

Materials Declaration

Package	LFCSP
Body Size	7 X 7
LeadCount	48
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy Resin	10	4.99 E-03	39544
SiO2 Filler	85	4.25 E-02	336123
Phenol Resin	5	2.50 E-03	19772

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	6.50 E-02	514996
Fe	2.35	1.57 E-03	12413
P	0.03	2.00 E-05	158
Zn	0.12	8.01 E-05	634

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	1.35 E-03	10685

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.34 E-04	2644

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.00 E-03	7918

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	5.97 E-03	47254

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	2.48 E-04	1965
Ag Filler	75	7.44 E-04	5894

Package Totals

Weight (g)	PPM
1.26 E-01	1000000

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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

5/19/04

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Package	LFCSP
Body Size	7 X 7
LeadCount	48
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy Resin	10	4.99 E-03	39544
SiO2 Filler	85	4.25 E-02	336123
Phenol Resin	5	2.50 E-03	19772

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	6.50 E-02	514996
Fe	2.35	1.57 E-03	12413
P	0.03	2.00 E-05	158
Zn	0.12	8.01 E-05	634

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	1.35 E-03	10685

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.84 E-04	2247
Pb	15	5.01 E-05	397

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.00 E-03	7918

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	5.97 E-03	47254

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	2.48 E-04	1965
Ag Filler	75	7.44 E-04	5894

Package Totals

Weight (g)	PPM
1.26 E-01	1000000

AMK-CP-A

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